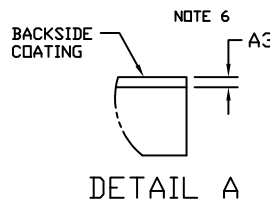
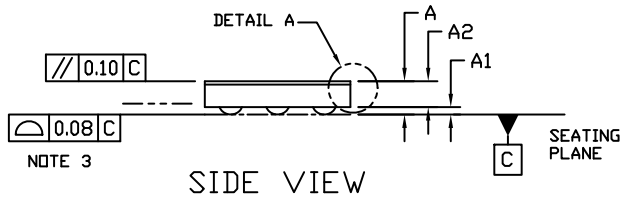
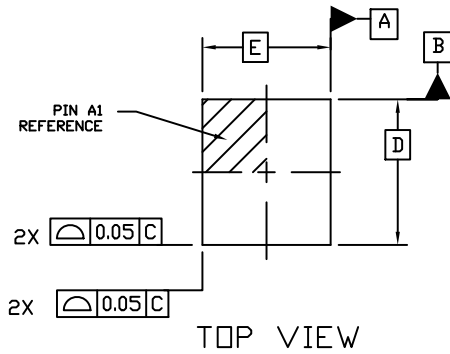


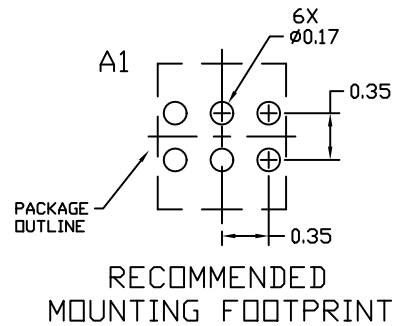
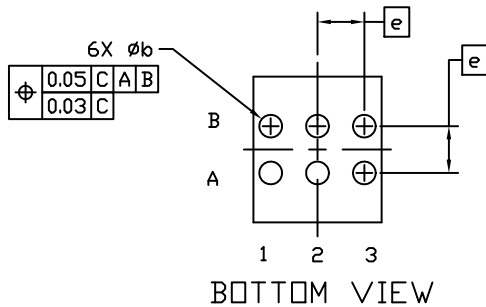


WLCSP6, 1.09x0.96x0.3
CASE 567WC
ISSUE O

DATE 13 MAR 2018



DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.30
A1	0.045	0.065
A2	0.195 REF	
A3	0.025 REF	
b	0.15	0.19
D	1.09 BSC	
E	0.96 BSC	
e	0.35 BSC	



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP6, 1.09x0.96x0.3	PAGE 1 OF 1

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